COPPER ALLOY FOR DC WIRING MATERIAL

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Abstract

PURPOSE:To obtain a Cu alloy for a DC wiring material having high strength and electrical conductivity and hardly causing a short circuit even when allowed to stand in a highly humid environment by specifying a compsn. consisting of Ni, Si and Cu.
CONSTITUTION:This Cu alloy for a DC wiring material consists of 0.4-4.0wt% Ni, 0.1-1.0wt% Si, 0.001-3.0wt% in total of one or more among Z, P, Sn, As, Cr, Mg, Mn, Sb, Fe, Co, Al, Ti, Zr, Be, Ag, Pb, B and lanthanoids as secondary components and the balance Cu with inevitable impurities. The Cu alloy has high mechanical strength and electrical conductivity and hardly causes a short circuit due to the deposition of Cu ions in a highly humid environment.